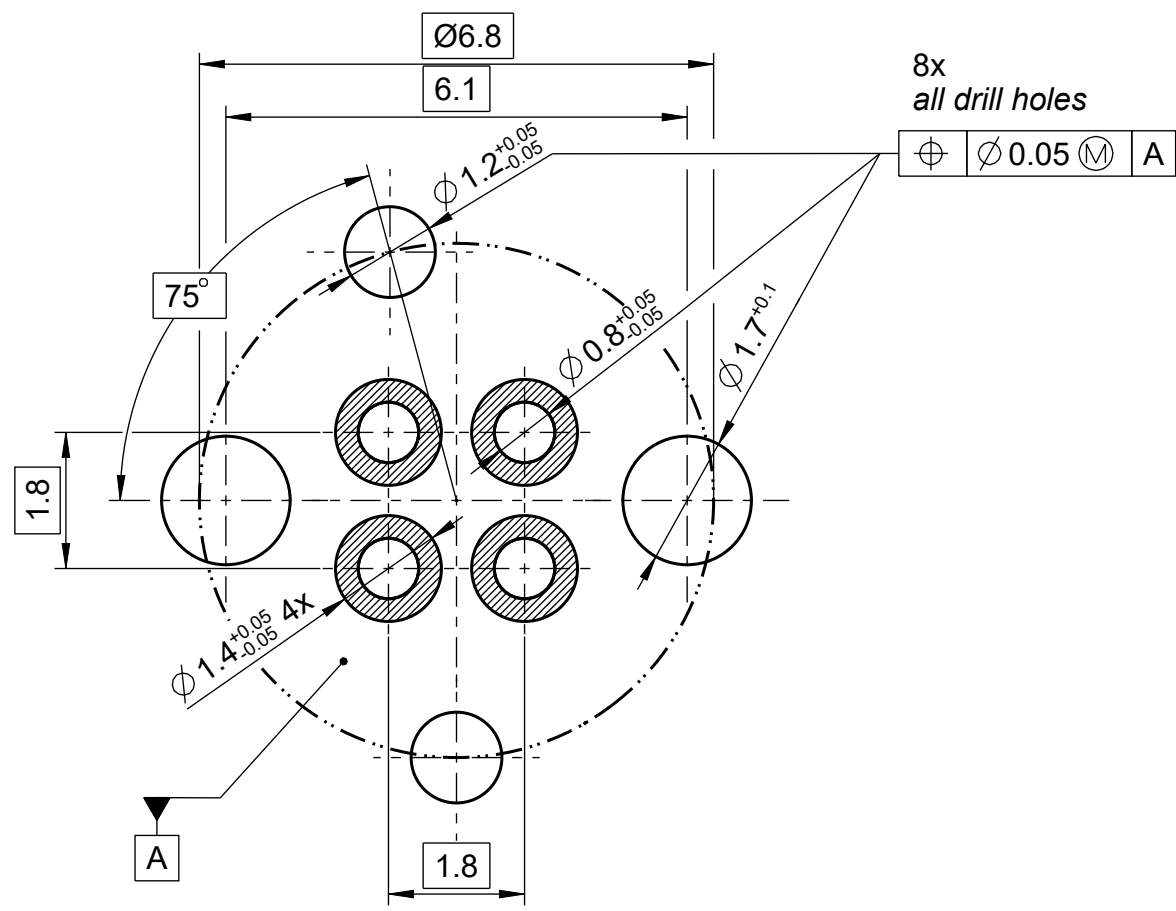


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1) Alle schraffierte Bohrungen kontaktieren mit Restringen auf der Rückseite durch. (Restringbreite min. 0.2mm)
 All hatched holes plate through inclusive pads on the backside. (padwidth min. 0.2mm)

Leiterplatten-Layout
 PCB-layout
 B 552



Die angegebenen Maße und Toleranzen sind nur Empfehlungen.
 The stated dimensions are only recommendations.

A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector. Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector. In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Rosenberger		general tolerance		scale: 10:1 ()	weight[g]: 13.525
		ISO 2768	RN 006-01	material:	
vertraulich / confidential		mH		title:	
		date	name	Leiterplatten-Layout PCB layout	
		drawn	04.12.2015 S_Gruendler		
		check	23.08.2018 N_Naus		
		appr.	30.08.2018 M_Wollweber		
		dimensioning incl. plating		drawing-no.:	sheet: 1
a00	18-s263	P_Leuschner	30.07.2018	MB_552	of: 1
200	18-1243	P_Leuschner	19.07.2018		remarks: .
100	15-m791	B_Doering	11.12.2015		
rev.	change-no	name	date		

PD_FB_01

-METRIC-



ISO-Projektion
 Methode 1